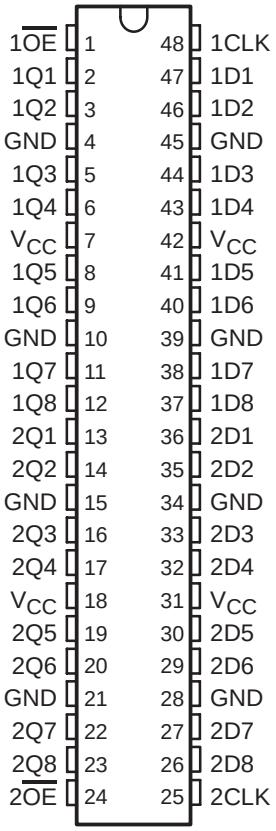
- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (−32-mA I_{OH}, 64-mA I_{OL})**
- **Packaged in Plastic 300-mil Shrink Small-Outline Packages (DL) and 380-mil Fine-Pitch Ceramic Flat Packages (WD) Using 25-mil Center-to-Center Spacings**

SN54ABT16374 . . . WD PACKAGE
SN74ABT16374 . . . DL PACKAGE
(TOP VIEW)



description

The ’ABT16374 is a 16-bit edge-triggered D-type flip-flop with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The device can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels set up at the data (D) inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components

The output enable ($\overline{OE}$) does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ABT16374 is packaged in TI’s shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN54ABT16374 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74ABT16374 is characterized for operation from −40°C to 85°C.

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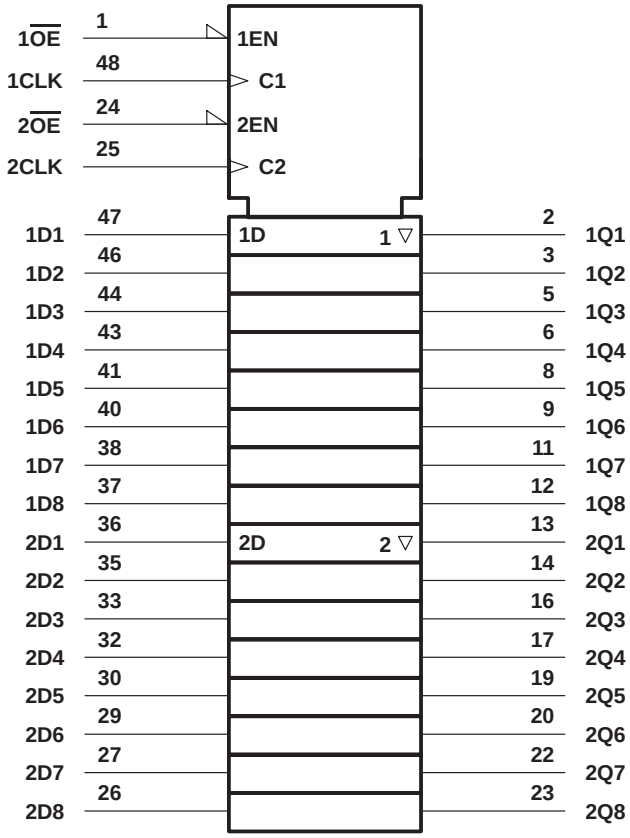
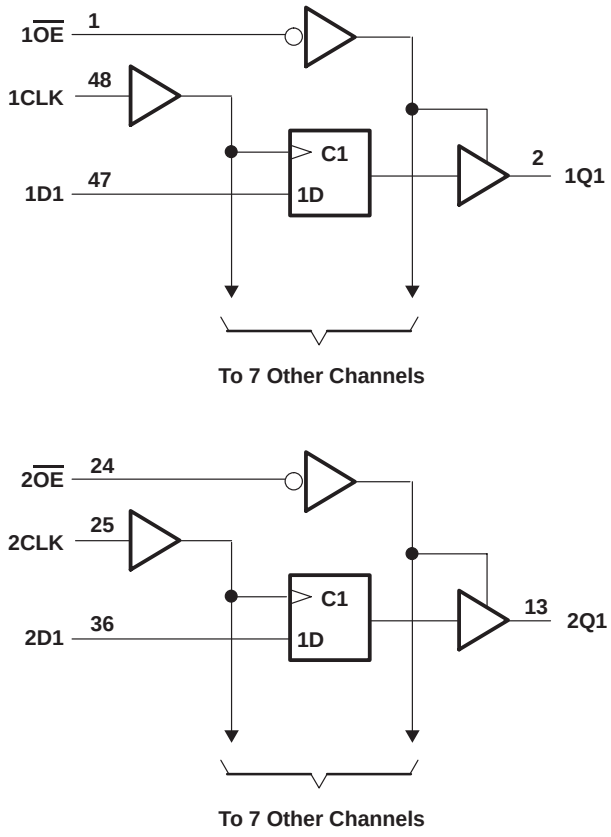
FUNCTION TABLE
(each flip-flop)

INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	H or L	X	Q_0
H	X	X	Z

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . . −0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V_O . . . . . −0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16374 . . . . . 96 mA
SN74ABT16374 . . . . . 128 mA
Input clamp current, I_{IK} (V_I < 0) . . . . . −18 mA
Output clamp current, I_{OK} (V_O < 0) . . . . . −50 mA
Maximum power dissipation at T_A = 55°C (in still air) . . . . . 0.85 W
Storage temperature range . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

			SN54ABT16374		SN74ABT16374		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			−24		−32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 2: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			T_A = 25°C			SN54ABT16374		SN74ABT16374		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = −18 mA				−1.2		−1.2		−1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = − 3 mA		2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = − 3 mA		3			3		3		
	V_{CC} = 4.5 V,	I_{OH} = −24 mA		2			2				
	V_{CC} = 4.5 V,	I_{OH} = − 32 mA		2‡					2		
V_{OL}	V_{CC} = 4.5 V,	I_{OL} = 48 mA				0.55		0.55			V
	V_{CC} = 4.5 V,	I_{OL} = 64 mA				0.55‡				0.55	
I_I	V_{CC} = 5.5 V,	V_I = V_{CC} or GND				±1		±1		±1	µA
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V				50		50		50	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.5 V				−50		−50		−50	µA
I_{OFF}	V_{CC} = 0,	V_I or V_O ≤ 4.5 V				±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V,	V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§	V_{CC} = 5.5 V,	V_O = 2.5 V		−50	−100	−180	−50	−180	−50	−180	mA
I_{CC}	V_{CC} = 5.5 V, V_I = V_{CC} or GND	I_O = 0,	Outputs high			2		2		2	mA
			Outputs low			67		67		67	
			Outputs disabled			2		2		2	
ΔI_{CC}¶	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND					1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V				3.5						pF
C_o	V_O = 2.5 V or 0.5 V				9.5						pF

† All typical values are at V_{CC} = 5 V.
‡ On products compliant to MIL-STD-883, Class B, this parameter does not apply.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

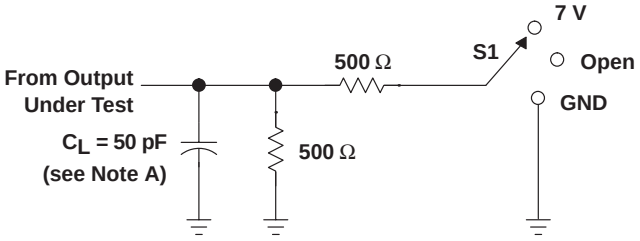
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		V_{CC} = 5 V, T_A = 25°C		SN54ABT16374		SN74ABT16374		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	0	150	0	150	0	150	MHz
t_w	Pulse duration, CLK high or low	3.3		3.3		3.3		ns
t_{su}	Setup time, data before CLK↑	1.1		1.1		1.1		ns
t_h	Hold time, data after CLK↑	1.3		1.3		1.3		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

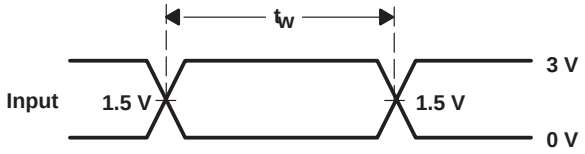
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16374		SN74ABT16374		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			150			150		150		MHz
t_{PLH}	CLK	Q	1.8	4.3	5.4	1.8	6.4	1.8	6.2	ns
t_{PHL}			2.7	4.5	5.6	2.7	6.4	2.7	5.9	
t_{PZH}	$\overline{OE}$	Q	1.4	3.6	4.8	1.4	6.1	1.4	5.7	ns
t_{PZL}			1.7	3.5	4.6	1.7	5.5	1.7	5.3	
t_{PHZ}	$\overline{OE}$	Q	2.2	5.4	8.4	2.2	11	2.2	10	ns
t_{PLZ}			2.3	4.6	7.7	2.3	9.8	2.3	8.7	

PARAMETER MEASUREMENT INFORMATION

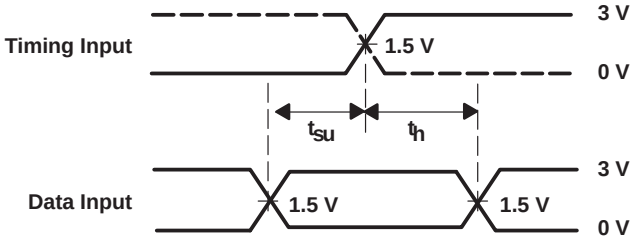


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

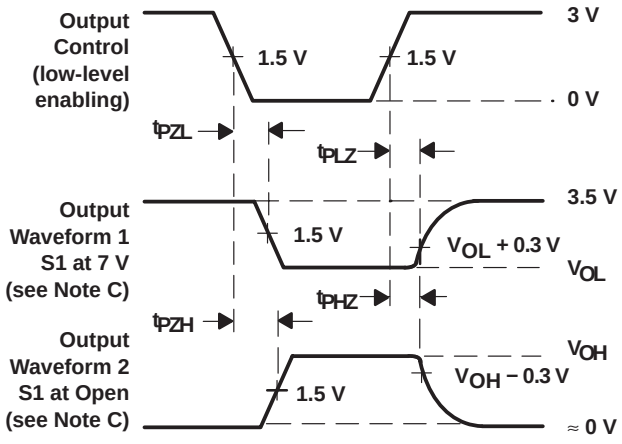
LOAD CIRCUIT FOR OUTPUTS



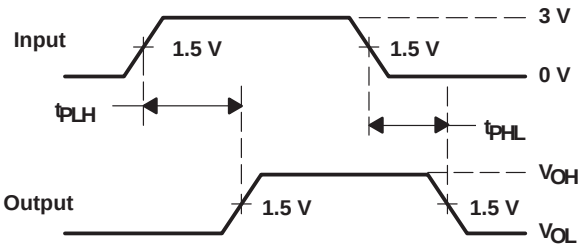
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
SN74ABT16374DGGR	OBSOLETE	TSSOP	DGG	48		TBD	Call TI	Call TI
SN74ABT16374DL	OBSOLETE	SSOP	DL	48		TBD	Call TI	Call TI
SN74ABT16374DL	OBSOLETE	SSOP	DL	48		TBD	Call TI	Call TI
SN74ABT16374DLR	OBSOLETE	SSOP	DL	48		TBD	Call TI	Call TI
SN74ABT16374DLR	OBSOLETE	SSOP	DL	48		TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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